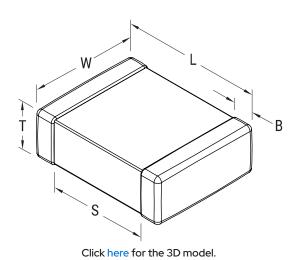


# C2225C241KHGACTU

Aliases (C2225C241KHGAC7800) SMD Comm COG HV, Ceramic, 240 pF, 10%, 3,000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2225, 3.2 mm



General Information			
Series	SMD Comm COG HV		
Style	SMD Chip		
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I		
Features	Ultra-Stable, Low Loss, Class I		
RoHS	Yes		
Termination	Tin		
Marking	No		
AEC-Q200	No		
Typical Component Weight	370 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions	
Chip Size	2225
L	5.6mm +/-0.4mm
W	6.4mm +/-0.4mm
Т	1.6mm +/-0.20mm
S	3.2mm MIN
В	0.6mm +/-0.35mm

Packaging Specifications		Capacitance Change	
			Temp. Coefficient
	В	0.6mm +/-0.35mm	Temperature Range
	S	3.2mm MIN	Dielectric Withstandi
	Т	1.6mm +/-0.20mm	Voltage DC
	W	6.4mm +/-0.4mm	Tolerance
	L	5.6mm +/-0.4mm	Measurement Condit

Specifications	
Capacitance	240 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	3000 VDC
Dielectric Withstanding Voltage	3,600 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 08/20/2025 © 2006 - 2025 YAGEO

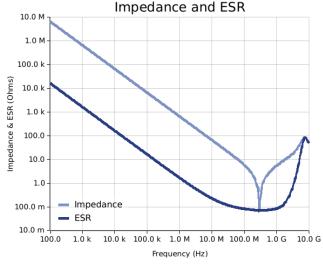


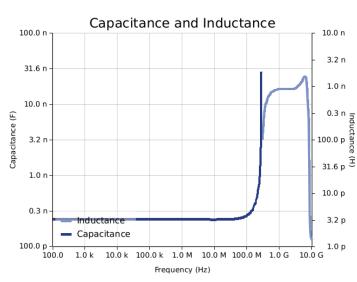
# C2225C241KHGACTU

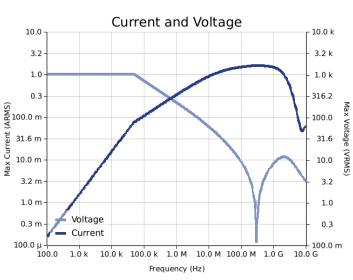
Aliases (C2225C241KHGAC7800) SMD Comm COG HV, Ceramic, 240 pF, 10%, 3,000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2225, 3.2 mm

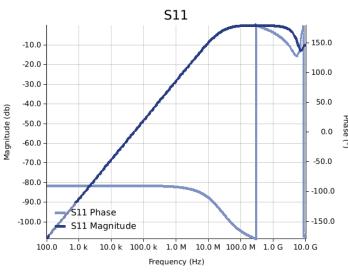
### **Simulations**

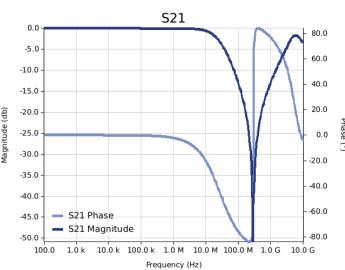
For the complete simulation environment please visit K-SIM.

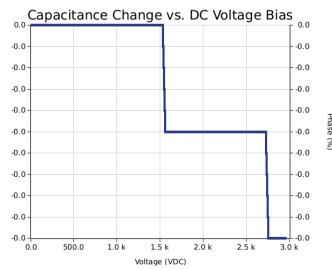












Generated 08/20/2025 © 2006 - 2025 YAGEO



### C2225C241KHGACTU

Aliases (C2225C241KHGAC7800) SMD Comm COG HV, Ceramic, 240 pF, 10%, 3,000 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 2225, 3.2 mm

#### These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR in the "Temperature Rise vs. Ripple Current" plots is the ESR at ambient temperature. The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated. The effects shown herein are based on measured data from a multiple part sample of the parts in question. Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

  Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

Generated 08/20/2025 © 2006 - 2025 YAGEO